

PS7341C-1A, PS7341CL-1A

CURRENT LIMIT TYPE 6-PIN DIP, HIGH ISOLATION VOLTAGE 1-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7341C-1A and PS7341CL-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs including current control circuit on the output side. Current control circuit of OCMOS FET protects this device from thermal breakdown and output circuit.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7341CL-1A has a surface mount type lead.

FEATURES

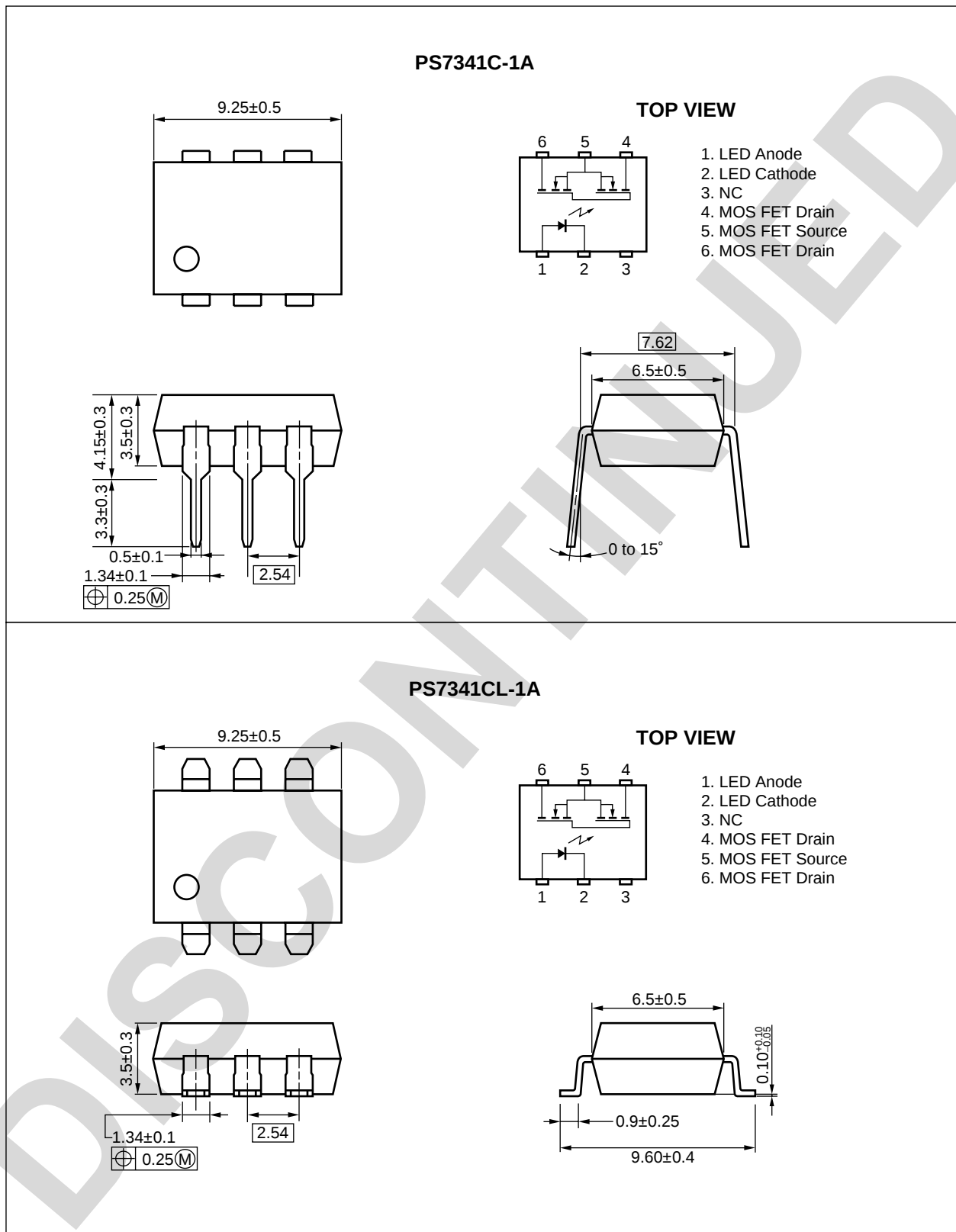
- Limit current ($I_{LMT} = 125$ to 250 mA)
- High isolation voltage ($BV = 3\,750$ Vr.m.s.)
- 1 channel type (1 a output)
- Low LED operating current ($I_F = 2$ mA)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- Ordering number of taping product : PS7341CL-1A-E3, E4: 1 000 pcs/reel
- <R> • Pb-Free product
- <R> • Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8252/8253
 - CSA approved: No. CA 101391
 - SEMKO approved: No. 606398
 - DEMKO approved: No. 309836
 - NEMKO approved: No. P00100964
 - FIMKO approved: No. FI 15188
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

APPLICATIONS

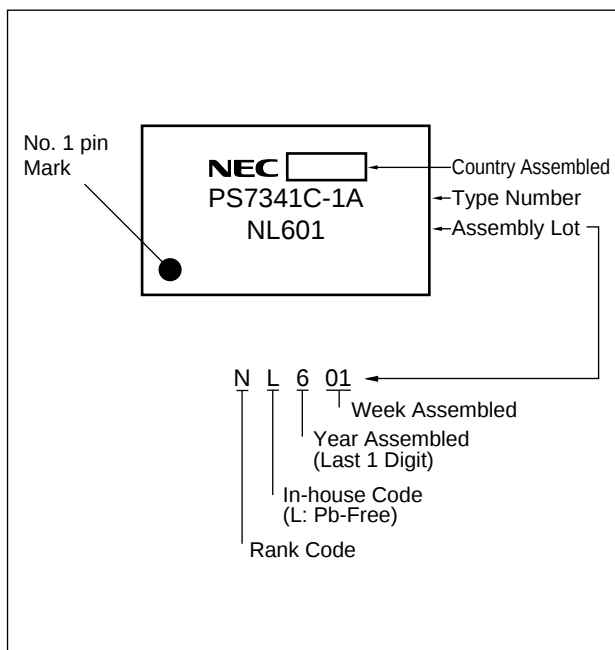
- Exchange equipment
- Measurement equipment
- FA/OA equipment

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PACKAGE DIMENSIONS (in millimeters)



<R> **MARKING EXAMPLE**



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7341C-1A	PS7341C-1A-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7341C-1A
PS7341CL-1A	PS7341CL-1A-A			(UL, BSI, CSA, SEMKO,	
PS7341CL-1A-E3	PS7341CL-1A-E3-A		Embossed Tape 1 000 pcs/reel	DEMKO, NEMKO,	
PS7341CL-1A-E4	PS7341CL-1A-E4-A			FIMKO approved)	

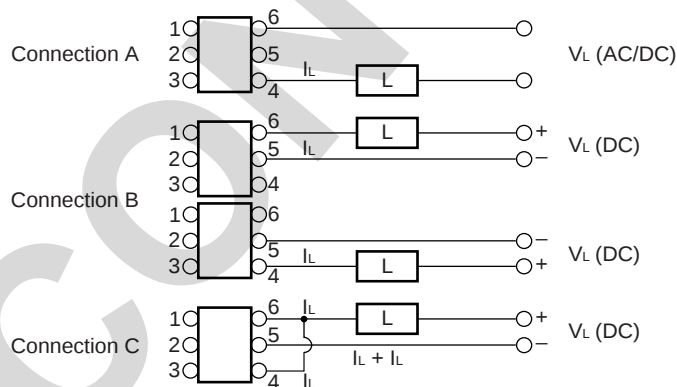
^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (DC)		I _F	50	mA
	Reverse Voltage		V _R	5.0	V
	Power Dissipation		P _D	50	mW
	Peak Forward Current *1		I _{FP}	1	A
MOS FET	Break Down Voltage		V _L	400	V
	Continuous Load Current *2	Connection A	I _L	120	mA
		Connection B		120	
		Connection C		240	
	Pulse Load Current *3 (AC/DC Connection)		I _{LP}	120	mA
	Power Dissipation		P _D	560	mW
Isolation Voltage *4			BV	3 750	Vr.m.s.
Total Power Dissipation			P _T	610	mW
Operating Ambient Temperature			T _A	−40 to +85	°C
Storage Temperature			T _{stg}	−40 to +125	°C

^{*1} $PW = 100 \mu\text{s}$, Duty Cycle = 1%

^{*2} Conditions: $I_F \geq 2 \text{ mA}$. The following types of load connections are available.



^{*3} $PW = 100 \text{ ms}$, 1 shot

^{*4} AC voltage for 1 minute at $T_A = 25^\circ\text{C}$, $RH = 60\%$ between input and output
Pins 1-3 shorted together, 4-6 shorted together.

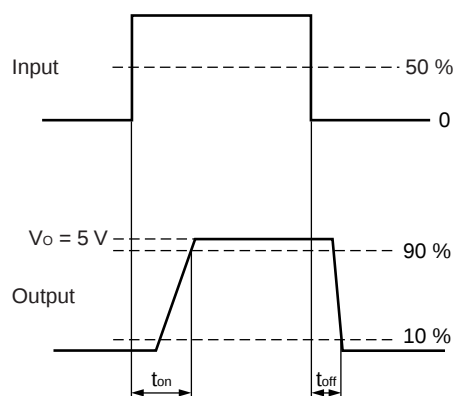
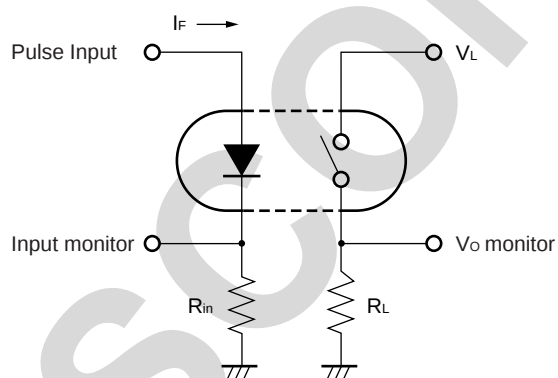
RECOMMENDED OPERATING CONDITIONS ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$		1.2	1.4	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5.0	μA
MOS FET	Off-state Leakage Current	I_{Leak}	$V_D = 400\text{ V}$		0.001	1.0	μA
	Output Capacitance	C_{out}	$V_D = 0\text{ V}$, $f = 1\text{ MHz}$		63		pF
Coupled	LED On-state Current	I_{Fon}	$I_L = 120\text{ mA}$			2.0	mA
	On-state Resistance	R_{on1}	$I_F = 10\text{ mA}$, $I_L = 10\text{ mA}$		27	35	Ω
		R_{on2}	$I_F = 10\text{ mA}$, $I_L = 120\text{ mA}$, $t \leq 10\text{ ms}$		22	30	
	Turn-on Time ^{*1,2}	t_{on}	$I_F = 10\text{ mA}$, $V_O = 5\text{ V}$, $R_L = 2\text{ k}\Omega$, $PW \geq 10\text{ ms}$		0.55	1.0	ms
	Turn-off Time ^{*1,2}	t_{off}			0.07	1.0	
	Isolation Resistance	$R_{\text{I-O}}$	$V_{\text{I-O}} = 1.0\text{ kV}_{\text{DC}}$	10^9			Ω
	Isolation Capacitance	$C_{\text{I-O}}$	$V = 0\text{ V}$, $f = 1\text{ MHz}$		1.1		pF
	Limit Current ^{*3}	I_{LMT}	$I_F = 10\text{ mA}$, $t = 5\text{ ms}$, $V_L = 6\text{ V}$	125	200	250	mA

*1 Test Circuit for Switching Time



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*2 The turn-on time and turn-off time are specified as input-pulse width $\geq 10\text{ ms}$.

Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

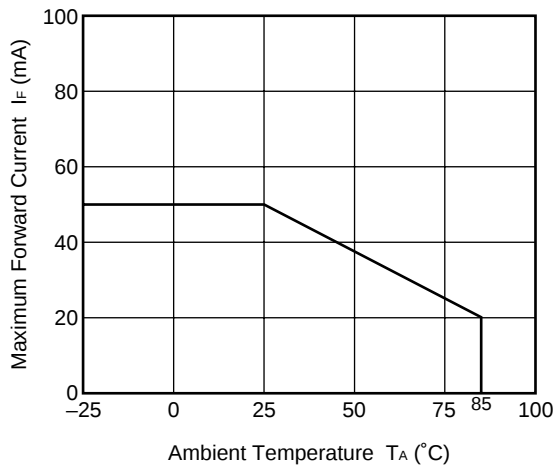
*3 N rank : 125 to 250 mA

M rank : 125 to 180 mA

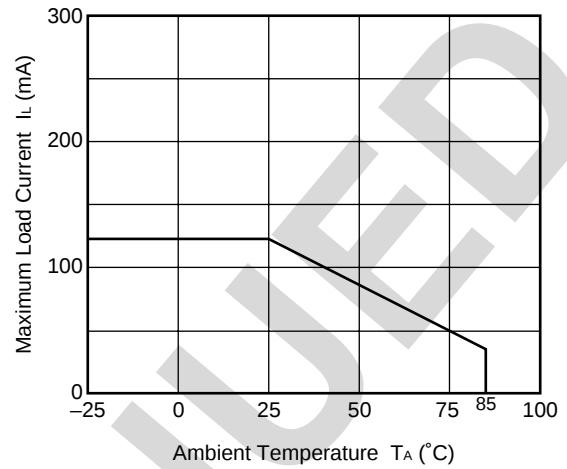
L rank : 170 to 250 mA

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

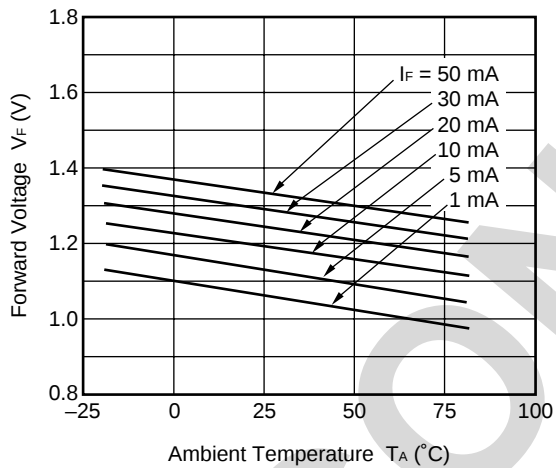
MAXIMUM FORWARD CURRENT vs.
AMBIENT TEMPERATURE



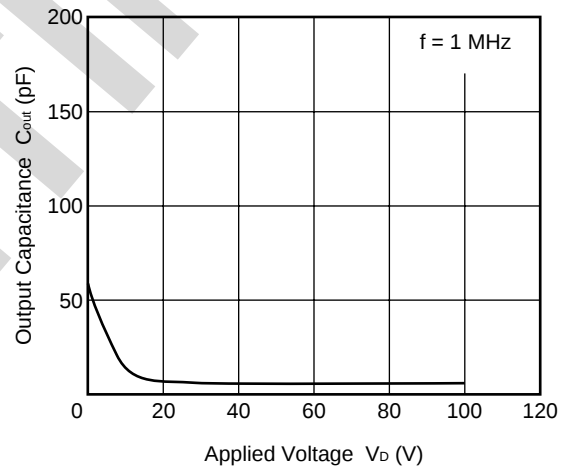
MAXIMUM LOAD CURRENT vs.
AMBIENT TEMPERATURE



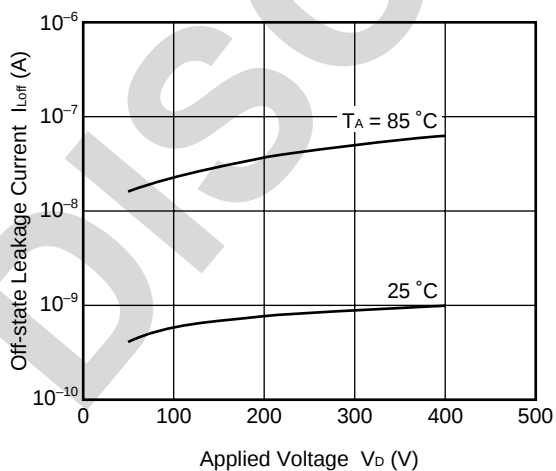
FORWARD VOLTAGE vs.
AMBIENT TEMPERATURE



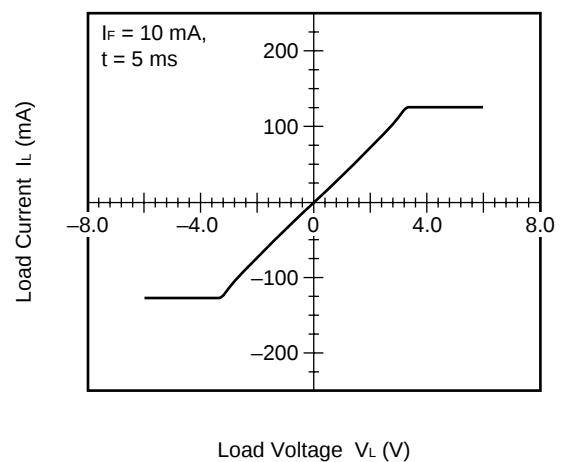
OUTPUT CAPACITANCE vs.
APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs.
APPLIED VOLTAGE

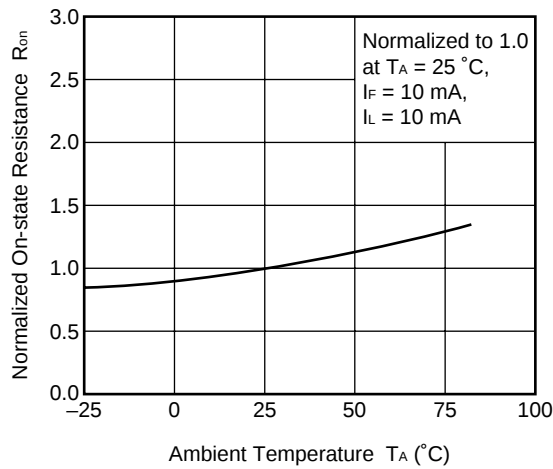


LOAD CURRENT vs. LOAD VOLTAGE

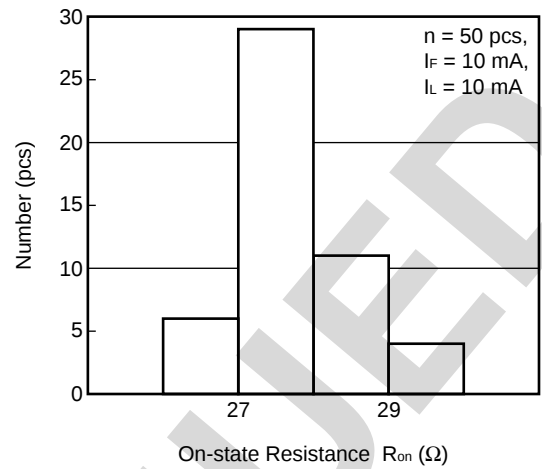


Remark The graphs indicate nominal characteristics.

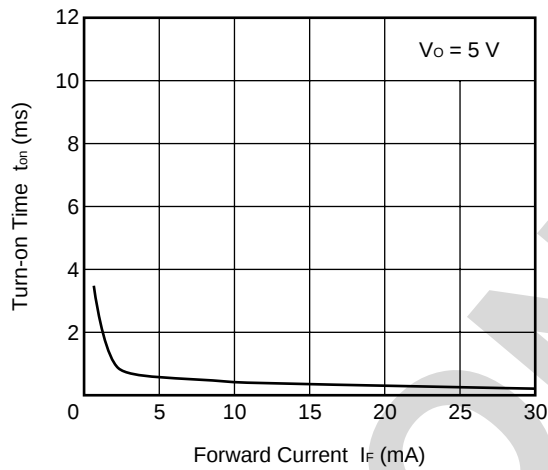
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



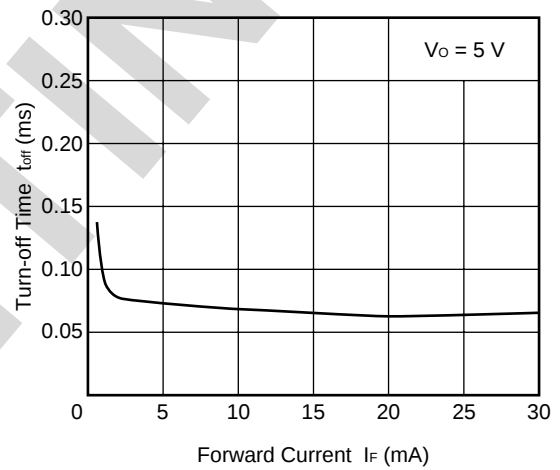
ON-STATE RESISTANCE DISTRIBUTION



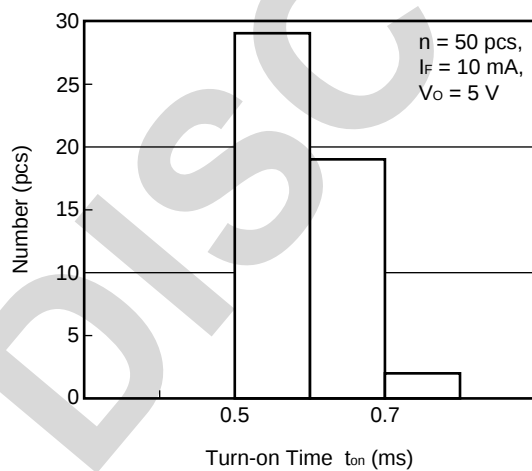
TURN-ON TIME vs. FORWARD CURRENT



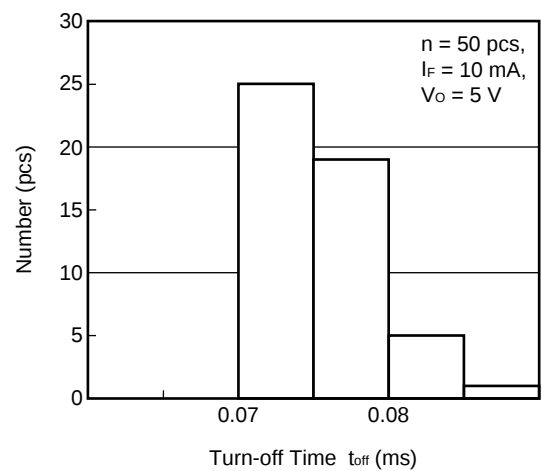
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

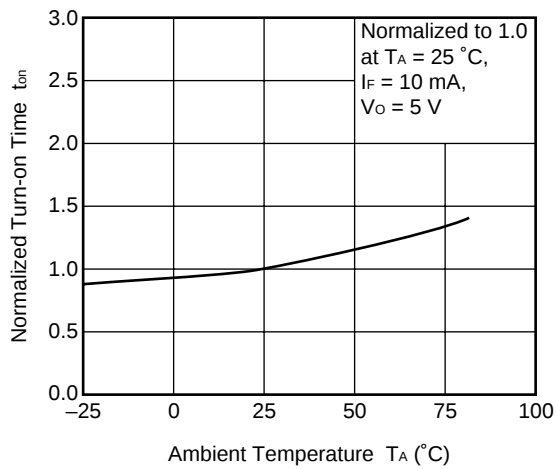


TURN-OFF TIME DISTRIBUTION

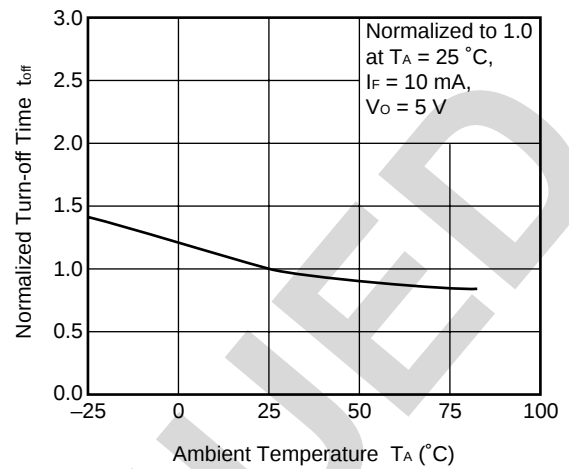


Remark The graphs indicate nominal characteristics.

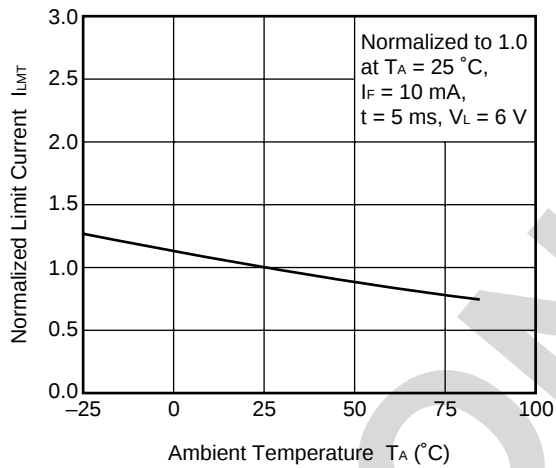
NORMALIZED TURN-ON TIME vs.
AMBIENT TEMPERATURE



NORMALIZED TURN-OFF TIME vs.
AMBIENT TEMPERATURE



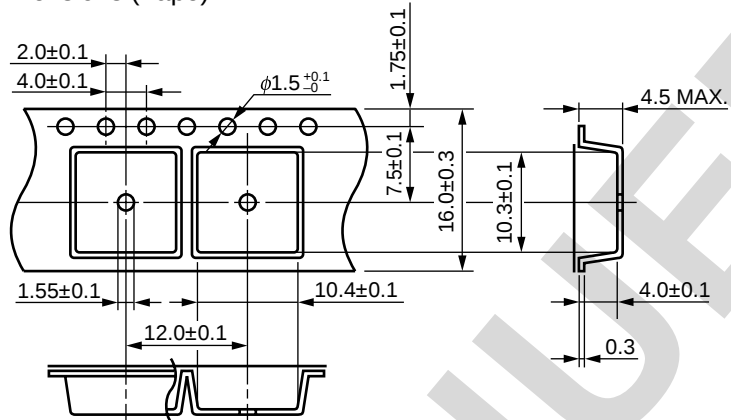
NORMALIZED LIMIT CURRENT vs.
AMBIENT TEMPERATURE



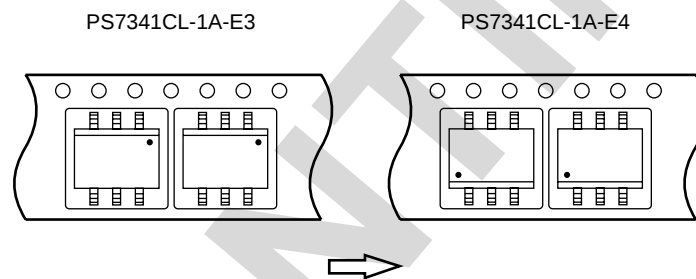
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)

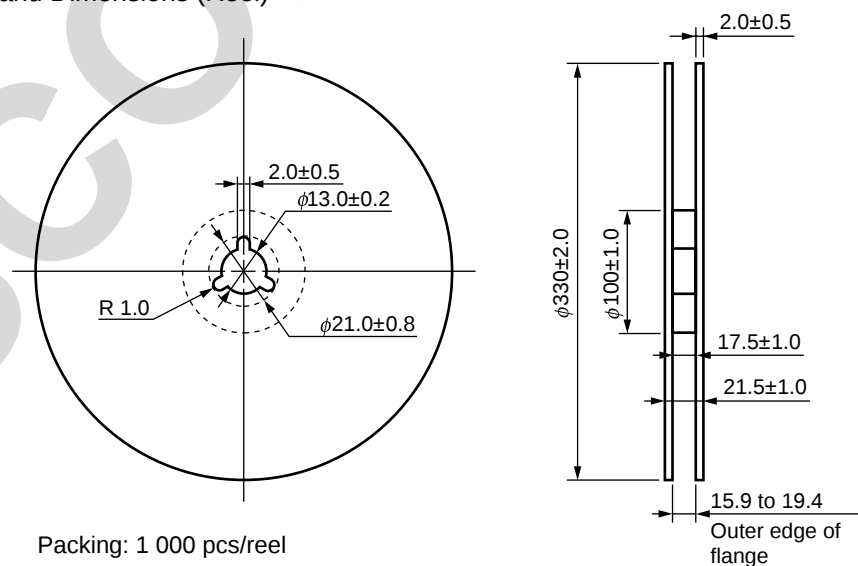
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

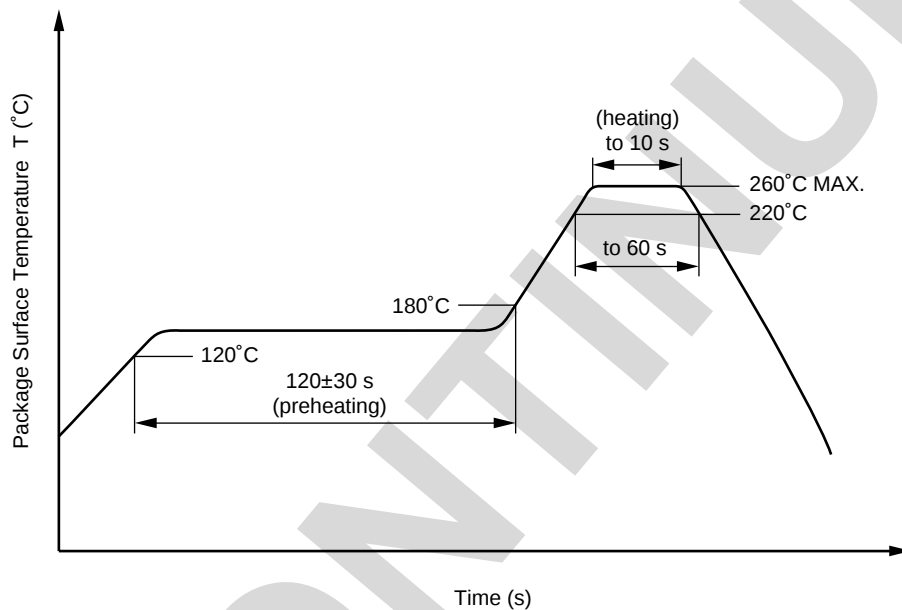


RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Two
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

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(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- <R>
- To avoid quality degradation, assembling within 1 month after take this device out from covered pack is required.
(Storage conditions 25°C, 65%RH MAX.)
 - Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> **USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

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► For further information, please contact

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